

Address: Shenzhen Bao 'an District Qianjin second Road Bao Yunda logistics information Building 12A11 606, Building A1, Hisense Industrial Park, 399 Songling Road, Laoshan District, Qingdao

P/N: HY160808 SRF07

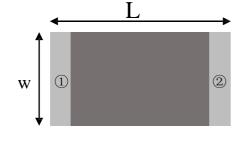
Features

- 1. Surface mounted devices with a small dimension of $1.6 \times 0.8 \times 0.8$ mm meet future miniaturization trend.
- 2. Embedded and LTCC (low temperature co-fired ceramic) technology is able to integrate with system design as well as beatifying the housing of final product.
- 3. High stability and low tolerance.

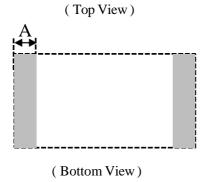
Applications

- 1. Bluetooth
- 2. Wireless LAN
- 3. ISM band 2.4GHz wireless applications

Dimensions (Unit: mm)



Number	Terminal Name
1	INPUT
2	NC

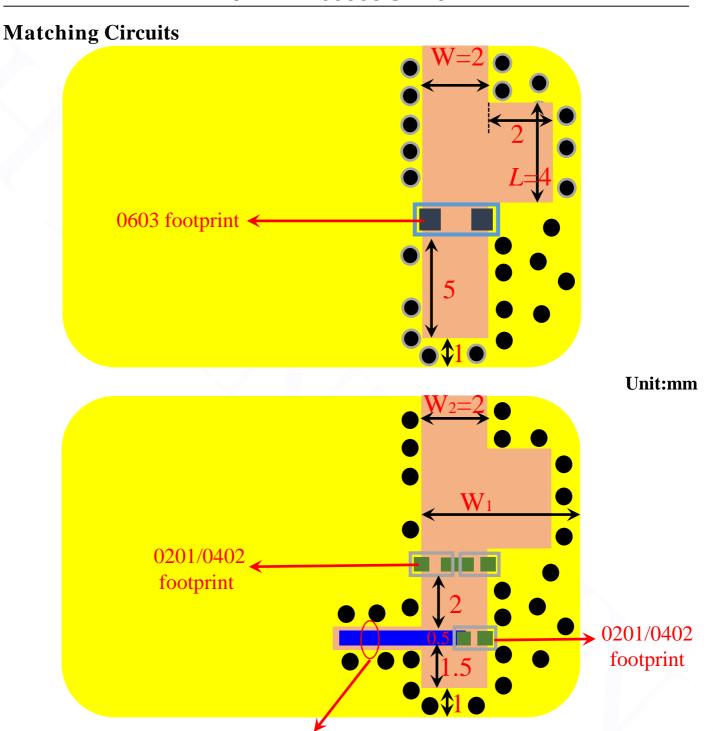




(Side View)

Symbols	L	W	Т	A	
Dimensions	Dimensions 1.60 ± 0.20		0.80 ± 0.20	0.30 ± 0.10	

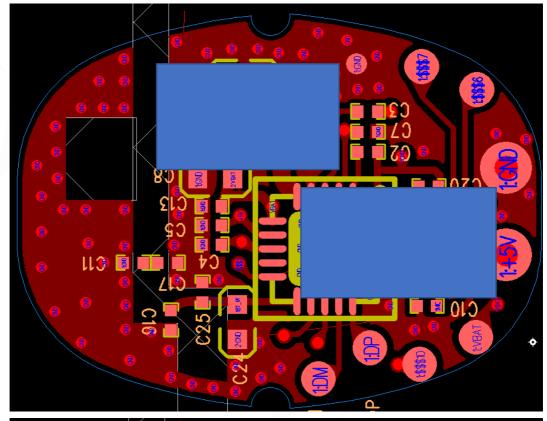


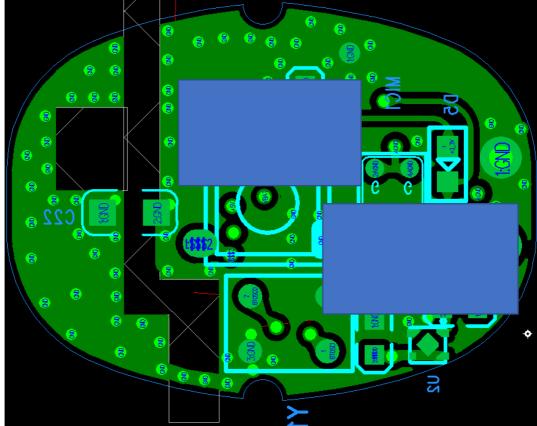


Hanyang Antenna Design Co. Ltd. has possession of proprietary information provided in this report and this proprietary information shall be kept in strict confidence and not disclosed to any person or firm without the prior written consent of Hanyang Antenna Design Co. Ltd.

Feeding line (微带线)

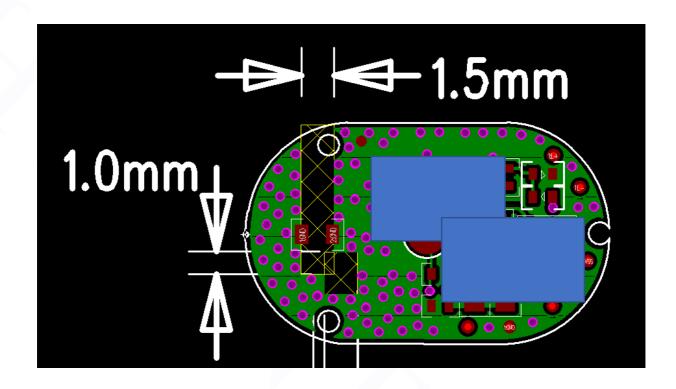
Application example-1

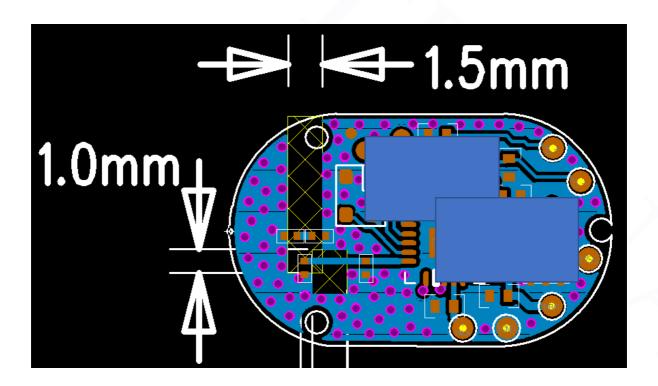






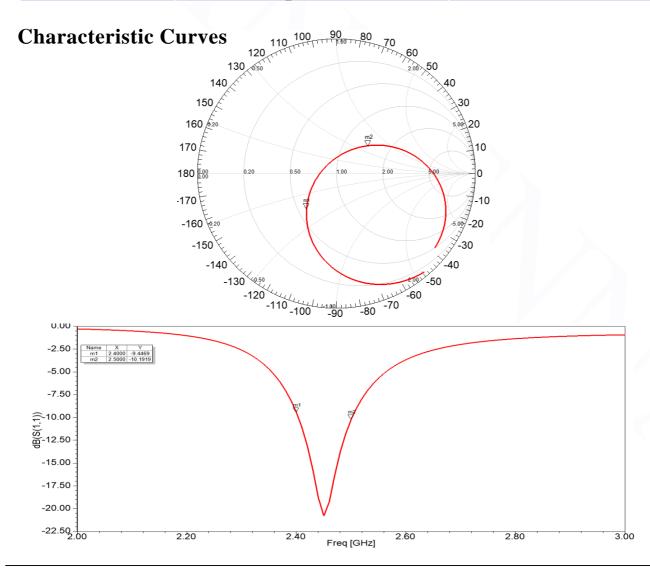
Application example-2

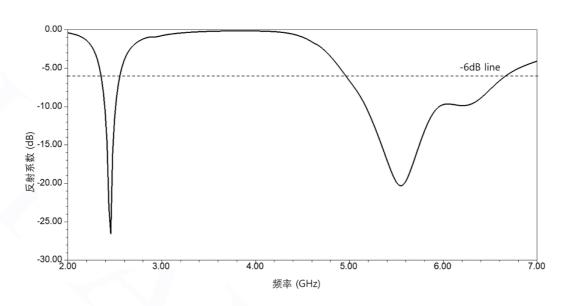




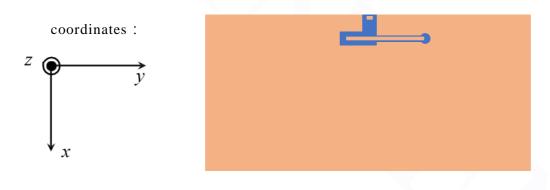
Electrical Characteristics

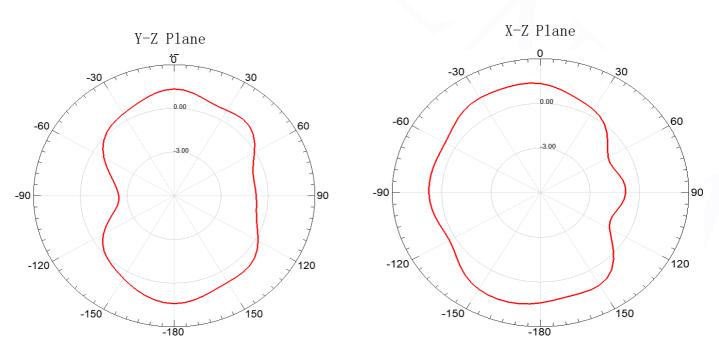
	Feature	Specification
1	Central frequency	2.45GHz&5.5GHz
2	Bandwidth	>100MHz
3	Peak gain	>3dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50Ω

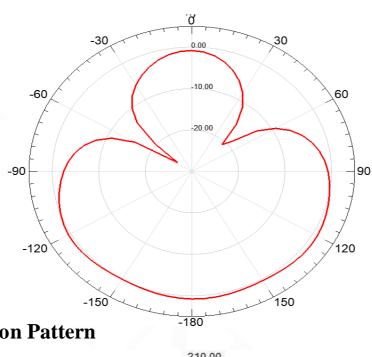




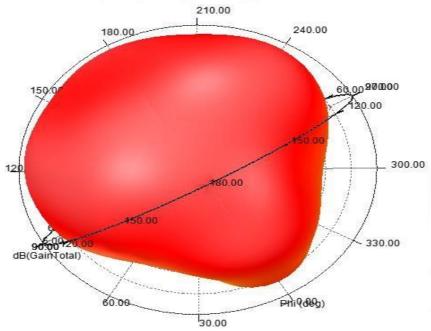
Radiation Pattern







3D Radiation Pattern



Frequency	2450MHz	5500MHz
Avg. gain	-0.85	-1.30
Peak gain	3.0	3.5
Efficiency	82%	78%

Dependability Test

Test Temperature $25^{\circ}\text{C} \pm 3^{\circ}\text{C}$ Operating Temperature $-25^{\circ}\text{C} \sim +85^{\circ}\text{C}$ Temperature $5\sim 40^{\circ}\text{C}$ Relative Humidity $20\sim 70\%$

Moisture Proof

Temperature: 40±2°C Humidity: 90~95%RH

Duration: 500h

Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

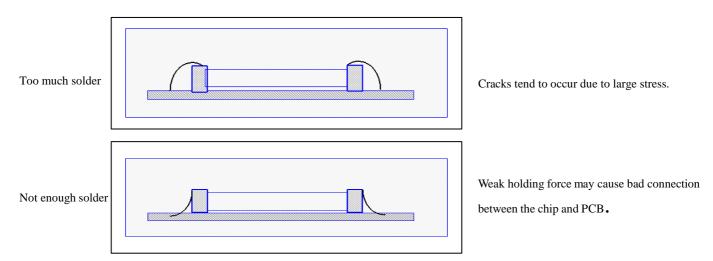
Solderability

At least 95% of the terminal electrode is covered by new solder.

Preheating conditions:80 to 120°C; 10~30s.

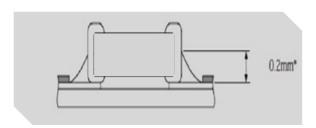
Solder Temperature: 235 ± 5°C Duration: 2 ± 0.5s, Solder Temperature: 245 ± 5°C Duration: 2 ± 0.5s

Optimum Solder Amount for Reflow Soldering

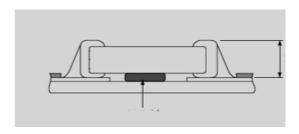


Recommended Soldering Amounts

The optimal solder fillet amounts for re-flow soldering



The optimal solder fillet amounts for wave soldering



Temperature Cycle Test

 10 ± 1 S Applied Force: 5N Duration: 10 ± 1 S Preheating conditions: up-category temperature, 1h

Recovery time: 24±1h Initial Measurement

Cycling Times: 5 times, 1 cycle, 4 steps:

阶段	温度(℃)	时间(分钟)
第1步	下限温度(NPO/X7R/X7S/X6S/X5R:-55)	30
第2步	常温 (+20)	2~3
第3步	上限温度(NPO/X7R/X78:+125 YSV/ZSU/X5R:+85 X68:+105)	30
第4步	常温 (+20)	2~3

Resistance to Soldering Heat

Preheating 80 to 120°C; 10~30s.SolderTemperature: 235±5°C; Duration: 2±0.5s; SolderTemperature: 245±5°C

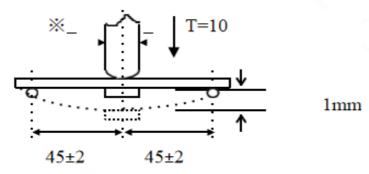
Duration: 2±0.5s; Preheating 100 to 200°C; 10±2min. Solder Temperature: 265±5°C; Duration: 10±1s

Clean the capacitor with solvent and examine it with a 10X(min.) microscope.

Recovery Time: 24±2h

Recovery condition: Room temperature

Resistance to Flexure of Substrate

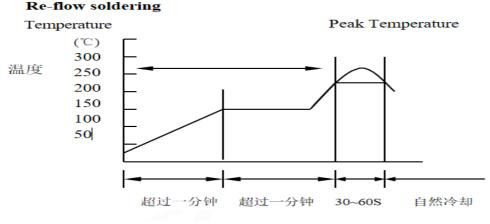


Test Board: Al₂O₃ or PCB Warp: 1mm Speed: 0.5mm/sec.

Unit: mm

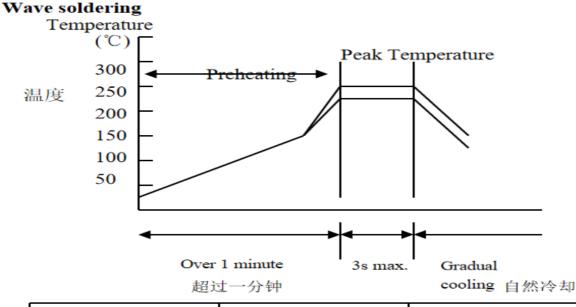
The measurement should be made with the board in the bending position.

The temperature profile for soldering



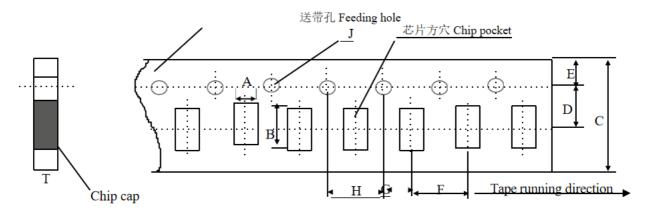
	Pb-Sn 焊接	无铅焊接		
	Pb-Sn soldering	Lead-free soldering		
尖峰温度 Peak temperature	230℃~250℃	240℃~260℃		

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \le 150$ °C.



	Pb-Sn 焊接	无铅焊接		
	Pb-Sn soldering	Lead-free soldering		
尖峰温度	230℃~260℃	240℃~270℃		
Peak temperature	2300 2000	2100 2700		

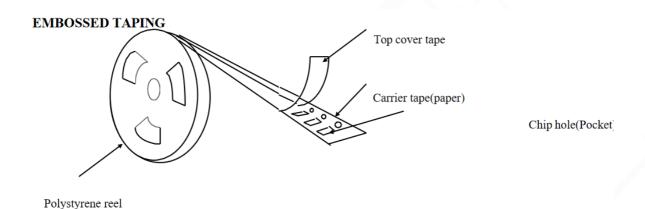
Dimensions of paper taping



Unit: mm

代号Code 纸带规格 papersize	A	В	С	D*	E	F	G*	Н	J	T
尺寸	1.10	1.90	8.00	3.50	1.75	4.00	2.00	4.00	1.50	1.10
<u></u>	±0.10	±0.10	±0.10	±0.05	±0.10	±0.10	±0.10	±0.10	-0/+0.10	Max

Reel (4000 pcs/Reel)



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature:5~40°C /Relative Humidity:20~70%